

SYSTEM AND METHOD FOR PROVIDING A REDISTRIBUTION  
METAL LAYER IN AN INTEGRATED CIRCUIT

ABSTRACT OF THE DISCLOSURE

5           A system and method is disclosed for providing a  
redistribution metal layer in an integrated circuit. The  
redistribution metal layer is formed from the last metal  
layer in the integrated circuit during manufacture of the  
integrated circuit before final passivation is applied. The  
10 last metal layer provides sites for solder bump pads used  
in flip chip interconnection. The redistribution metal  
layer can be (1) a flat layer deposited over the next to  
last metal layer through an opening in a dielectric layer,  
or (2) deposited over an array of vias connected to the  
15 next to last metal layer. Space between the solder bump  
pads is deposited with narrower traces for connecting  
active circuit areas below. A final passivation layer is  
deposited to ensure product reliability.